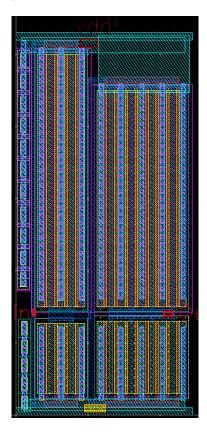
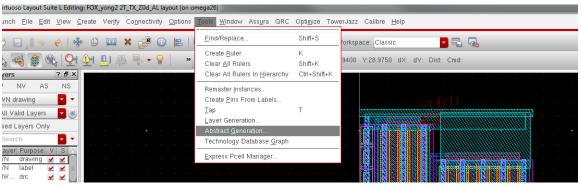
At this stage, we have had the layout of each block (we call it analog block) and we have the layout of the digital controller (from encounter)

- 1. Make lef file for the analog blocks
  - a. Open the analog block layout



# b. Generate abstract file



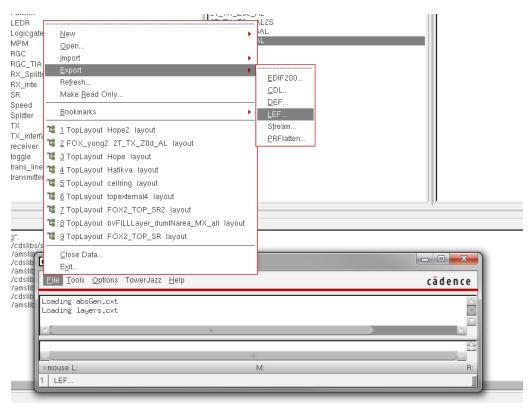


Then click → start

In this way, we can get the abstract file

View ^	Lock	Size
abstract		29k
abstract.ext		53k
abstract.pin		54k
abstract.scratch		0
省 layout	yong@omega26.technion.ac.il	53k
schematic		33k
symbol		23k

c. Export lef file



From the start window of virtuoso  $\rightarrow$  export  $\rightarrow$  lef

Manually set the library name, the output cell should be the cell you edited and the lef name should be the\*\*\*\*\*\*( cellname).lef and the output view should be abstract.



```
d. Edit the lef file
  VERSION 5.7;
  BUSBITCHARS "[]";
  DIVIDERCHAR "/";
  PROPERTY DEFINITIONS
   LAYER LEF58 TYPE STRING;
   LAYER LEF58 ENCLOSURE STRING;
   LAYER LEF58 SPACING STRING;
   LAYER LEF58 WIDTH STRING;
  END PROPERTY DEFINITIONS
  UNITS
   TIME NANOSECONDS 1;
   CAPACITANCE PICOFARADS 1;
   RESISTANCE OHMS 1;
   DATABASE MICRONS 1000;
  END UNITS
  MANUFACTURINGGRID 0.005;
  LAYER OverlapCheck
   TYPE OVERLAP;
  END OverlapCheck
  LAYER WN
   TYPE MASTERSLICE;
   PROPERTY LEF58 TYPE "TYPE NWELL;";
   PROPERTY LEF58 SPACING "SPACING 2.8;";
   PROPERTY LEF58 WIDTH "WIDTH 0.86;";
  END WN
  LAYER ACTIVE
   TYPE MASTERSLICE;
  END ACTIVE
  LAYER XP
   TYPE IMPLANT;
   WIDTH 0.44;
   SPACING 0.44;
  END XP
  LAYER XN
   TYPE IMPLANT;
   WIDTH 0.44;
   SPACING 0.44;
```

```
SPACING 0 LAYER XP;
END XN
LAYER GC
TYPE MASTERSLICE;
END GC
LAYER CS
 TYPE CUT;
 SPACING 0.25;
 WIDTH 0.22;
 ENCLOSURE BELOW 0.1 0.1;
 ENCLOSURE ABOVE 0.06 0.005;
 ANTENNAMODEL OXIDE1;
END CS
LAYER M1
TYPE ROUTING;
 DIRECTION HORIZONTAL;
 PITCH 0.56 0.56;
 WIDTH 0.23;
 AREA 0.202;
 SPACING 0.23;
 SPACING 0.6 RANGE 10 10000;
 SPACING 0.23 SAMENET;
 RESISTANCE RPERSQ 0.08;
 CAPACITANCE CPERSQDIST 3.51e-05;
 HEIGHT 1.05;
 THICKNESS 0.54;
 ANTENNAMODEL OXIDE1;
 ANTENNASIDEAREARATIO 400;
 ANTENNADIFFSIDEAREARATIO PWL ( ( 0 400 ) ( 0.203 400 ) ( 0.203001
2281.2)(1.203 2681.2));
END M1
LAYER V2
 TYPE CUT;
 SPACING 0.26;
 SPACING 0 LAYER CS;
 WIDTH 0.26;
 ENCLOSURE BELOW 0.06 0.01;
 ENCLOSURE ABOVE 0.06 0.01;
 ANTENNAMODEL OXIDE1;
 ANTENNAAREARATIO 20;
```

```
ANTENNADIFFAREARATIO PWL ( ( 0 20 ) ( 0.203 20 ) ( 0.203001 91.9161 )
(1.203175.246));
END V2
LAYER M2
 TYPE ROUTING;
 DIRECTION VERTICAL;
 PITCH 0.56 0.56;
 WIDTH 0.28;
 AREA 0.202;
 SPACING 0.28;
 SPACING 0.6 RANGE 10 10000;
 SPACING 0.28 SAMENET;
 RESISTANCE RPERSQ 0.08;
 CAPACITANCE CPERSQDIST 1.46e-05;
 HEIGHT 2.41;
 THICKNESS 0.54;
 ANTENNAMODEL OXIDE1;
 ANTENNASIDEAREARATIO 400;
 ANTENNADIFFSIDEAREARATIO PWL ( ( 0 400 ) ( 0.203 400 ) ( 0.203001
2281.2)(1.203 2681.2));
END M2
LAYER V3
 TYPE CUT;
 SPACING 0.26;
 SPACING 0 SAMENET LAYER V2 STACK;
 WIDTH 0.26;
 ENCLOSURE BELOW 0.06 0.01;
 ENCLOSURE ABOVE 0.06 0.01;
 ANTENNAMODEL OXIDE1;
 ANTENNAAREARATIO 20;
 ANTENNADIFFAREARATIO PWL ( ( 0 20 ) ( 0.203 20 ) ( 0.203001 91.9161 )
(1.203175.246));
END V3
LAYER M3
 TYPE ROUTING;
 DIRECTION HORIZONTAL;
 PITCH 0.56 0.56;
 WIDTH 0.28;
 AREA 0.202;
 SPACING 0.28;
 SPACING 0.6 RANGE 10 10000;
```

```
SPACING 0.28 SAMENET;
 RESISTANCE RPERSQ 0.08;
 CAPACITANCE CPERSQDIST 9.24e-06;
 HEIGHT 3.77;
 THICKNESS 0.54;
 ANTENNAMODEL OXIDE1;
 ANTENNASIDEAREARATIO 400;
 ANTENNADIFFSIDEAREARATIO PWL ( ( 0 400 ) ( 0.203 400 ) ( 0.203001
2281.2)(1.203 2681.2));
END M3
LAYER V4
 TYPE CUT;
 SPACING 0.26;
 SPACING 0 SAMENET LAYER V3 STACK;
 WIDTH 0.26;
 ENCLOSURE BELOW 0.06 0.01;
 ENCLOSURE ABOVE 0.06 0.01;
 ANTENNAMODEL OXIDE1;
 ANTENNAAREARATIO 20;
 ANTENNADIFFAREARATIO PWL ( ( 0 20 ) ( 0.203 20 ) ( 0.203001 91.9161 )
(1.203175.246));
END V4
LAYER M4
 TYPE ROUTING;
 DIRECTION VERTICAL;
 PITCH 0.56 0.56;
 WIDTH 0.28;
 AREA 0.202;
 SPACING 0.28;
 SPACING 0.6 RANGE 10 10000;
 SPACING 0.28 SAMENET;
 RESISTANCE RPERSQ 0.08;
 CAPACITANCE CPERSQDIST 6.75e-06;
 HEIGHT 5.13;
 THICKNESS 0.54;
 ANTENNAMODEL OXIDE1;
 ANTENNASIDEAREARATIO 400;
 ANTENNADIFFSIDEAREARATIO PWL ( ( 0 400 ) ( 0.203 400 ) ( 0.203001
2281.2)(1.203 2681.2));
END M4
LAYER V5
```

```
TYPE CUT;
 SPACING 0.26;
 SPACING 0 SAMENET LAYER V4 STACK;
 WIDTH 0.26:
 ENCLOSURE BELOW 0.06 0.01;
 ENCLOSURE ABOVE 0.06 0.01;
 ANTENNAMODEL OXIDE1;
 ANTENNAAREARATIO 20;
 ANTENNADIFFAREARATIO PWL ( ( 0 20 ) ( 0.203 20 ) ( 0.203001 91.9161 )
(1.203175.246));
END V5
LAYER M5
 TYPE ROUTING;
 DIRECTION HORIZONTAL;
 PITCH 0.84 0.84;
 WIDTH 0.28;
 AREA 0.202;
 SPACING 0.28;
 SPACING 0.6 RANGE 10 10000;
 SPACING 0.28 SAMENET;
 RESISTANCE RPERSQ 0.08;
 CAPACITANCE CPERSQDIST 5.32e-06;
 HEIGHT 6.49;
 THICKNESS 0.54;
 ANTENNAMODEL OXIDE1;
 ANTENNASIDEAREARATIO 400;
 ANTENNADIFFSIDEAREARATIO PWL ( ( 0 400 ) ( 0.203 400 ) ( 0.203001
2281.2)(1.203 2681.2));
END M5
LAYER TOP V
 TYPE CUT;
 SPACING 0.35;
 SPACING 0 SAMENET LAYER V5 STACK;
 WIDTH 0.36;
 ENCLOSURE BELOW 0.06 0.01;
 ENCLOSURE ABOVE 0.09 0.09;
 ANTENNAMODEL OXIDE1;
 ANTENNAAREARATIO 20;
 ANTENNADIFFAREARATIO PWL ( ( 0 20 ) ( 0.203 20 ) ( 0.203001 91.9161 )
(1.203175.246));
END TOP V
```

```
LAYER TOP M
 TYPE ROUTING;
 DIRECTION VERTICAL;
 PITCH 1.12 1.12;
 WIDTH 0.44;
 AREA 0.562;
 SPACING 0.46;
 SPACING 0.6 RANGE 10 10000;
 SPACING 0.46 SAMENET;
 RESISTANCE RPERSQ 0.04;
 CAPACITANCE CPERSQDIST 4.389e-06;
 HEIGHT 7.83;
 THICKNESS 0.84;
 ANTENNAMODEL OXIDE1;
 ANTENNASIDEAREARATIO 400;
 ANTENNADIFFSIDEAREARATIO PWL ( ( 0 400 ) ( 0.203 400 ) ( 0.203001
31624) (1.203 39624));
END TOP M
VIARULE ML M5 S GENERATE DEFAULT
LAYER M5;
 ENCLOSURE 0.01 0.01;
 LAYER TOP M;
 ENCLOSURE 0.09 0.09;
 LAYER TOP V;
 RECT -0.18 -0.18 0.18 0.18;
  SPACING 0.71 BY 0.71;
END ML M5 S
VIARULE M5 M4 S GENERATE DEFAULT
 LAYER M4;
 ENCLOSURE 0.01 0.01;
 LAYER M5;
 ENCLOSURE 0.01 0.01;
 LAYER V5;
 RECT -0.13 -0.13 0.13 0.13;
 SPACING 0.52 BY 0.52;
END M5 M4 S
VIARULE M4 M3 S GENERATE DEFAULT
 LAYER M3;
 ENCLOSURE 0.01 0.01;
 LAYER M4;
 ENCLOSURE 0.01 0.01;
```

```
LAYER V4;
 RECT -0.13 -0.13 0.13 0.13;
 SPACING 0.52 BY 0.52;
END M4 M3 S
VIARULE M3 M2 S GENERATE DEFAULT
LAYER M2;
 ENCLOSURE 0.01 0.01;
 LAYER M3;
 ENCLOSURE 0.01 0.01;
 LAYER V3;
 RECT -0.13 -0.13 0.13 0.13;
  SPACING 0.52 BY 0.52;
END M3 M2 S
VIARULE M2 M1 S GENERATE DEFAULT
LAYER M1;
 ENCLOSURE 0.01 0.01;
 LAYER M2;
 ENCLOSURE 0.01 0.01;
 LAYER V2;
 RECT -0.13 -0.13 0.13 0.13;
 SPACING 0.52 BY 0.52;
END M2 M1 S
VIARULE ML M5 GENERATE
LAYER M5;
 ENCLOSURE 0.06 0.06;
 LAYER TOP M;
 ENCLOSURE 0.09 0.09;
 LAYER TOP V;
 RECT -0.18 -0.18 0.18 0.18;
  SPACING 0.71 BY 0.71;
END ML M5
VIARULE M5 M4 GENERATE
LAYER M4;
 ENCLOSURE 0.06 0.06;
 LAYER M5;
 ENCLOSURE 0.06 0.06;
 LAYER V5;
 RECT -0.13 -0.13 0.13 0.13;
 SPACING 0.52 BY 0.52;
END M5 M4
```

```
VIARULE M4 M3 GENERATE
 LAYER M3;
 ENCLOSURE 0.06 0.06;
 LAYER M4;
 ENCLOSURE 0.06 0.06;
 LAYER V4;
 RECT -0.13 -0.13 0.13 0.13;
  SPACING 0.52 BY 0.52;
END M4 M3
VIARULE M3 M2 GENERATE
 LAYER M2;
 ENCLOSURE 0.06 0.06;
 LAYER M3;
 ENCLOSURE 0.06 0.06;
 LAYER V3;
 RECT -0.13 -0.13 0.13 0.13;
  SPACING 0.52 BY 0.52;
END M3 M2
VIARULE M2_M1 GENERATE
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER M2;
 ENCLOSURE 0.06 0.06;
 LAYER V2;
 RECT -0.13 -0.13 0.13 0.13;
  SPACING 0.52 BY 0.52;
END M2 M1
VIARULE M1 PO 4X GENERATE
 LAYER GC;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
  SPACING 0.5 BY 0.5;
END M1 PO 4X
VIARULE M1_PO GENERATE
 LAYER GC;
 ENCLOSURE 0.1 0.1;
```

```
LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
 SPACING 0.47 BY 0.47;
END M1 PO
VIARULE PTAP 4X LG GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
 SPACING 0.5 BY 0.5;
END PTAP 4X LG
VIARULE PTAP 4X GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
  SPACING 0.5 BY 0.5;
END PTAP 4X
VIARULE PTAP LG GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
  SPACING 0.47 BY 0.47;
END PTAP LG
VIARULE PTAP GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
```

```
SPACING 0.47 BY 0.47;
END PTAP
VIARULE NTAP 4X LG GENERATE
LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
  SPACING 0.5 BY 0.5;
END NTAP 4X LG
VIARULE NTAP 4X GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
  SPACING 0.5 BY 0.5;
END NTAP_4X
VIARULE NTAP LG GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
  SPACING 0.47 BY 0.47;
END NTAP LG
VIARULE NTAP GENERATE
 LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
 SPACING 0.47 BY 0.47;
END NTAP
VIARULE M1 WN GENERATE
```

```
LAYER ACTIVE;
 ENCLOSURE 0.1 0.1;
 LAYER M1;
 ENCLOSURE 0.06 0.06;
 LAYER CS;
 RECT -0.11 -0.11 0.11 0.11;
 SPACING 0.47 BY 0.47;
END M1 WN
SITE CoreSite hv
 CLASS CORE;
 SYMMETRY Y;
 SIZE 0.56 BY 6.16;
END CoreSite hv
MACRO 2T TX Z0d AL
 CLASS BLOCK;
 ORIGIN 00;
 FOREIGN 2T_TX_Z0d_AL 0 0;
 SIZE 12.25 BY 26.5;
 SYMMETRY X Y R90;
 PIN In
 DIRECTION INOUT;
 USE SIGNAL;
 PORT
  LAYER M1;
   RECT 1.115 6.85 1.345 7.305;
 END
 END In
 PIN gnd!
 DIRECTION INOUT;
 USE GROUND;
 PORT
  LAYER M2;
   RECT 5.13 0 5.365 1.105;
   RECT 4.735 0 6.22 0.715;
 END
 END gnd!
 PIN Out
 DIRECTION INOUT;
 USE SIGNAL;
 PORT
  LAYER M1;
   RECT 10.275 6.69 10.405 7.31;
```

```
RECT 10.275 6.865 11.005 7.15;
END
END Out
PIN vdd!
 DIRECTION INOUT;
USE POWER;
 PORT
 LAYER M2;
   RECT 5.13 25.105 5.31 26.065;
   RECT 4.49 25.51 5.67 26.065;
 END
END vdd!
OBS
 LAYER M1;
  RECT 0.335 8.975 0.715 25.895;
  RECT 0.4 0.43 0.78 6.43;
  RECT 1.115 7.905 1.345 25.775;
  RECT 1.115 0.77 1.345 6.25;
  RECT 1.575 1.54 1.805 6.31;
  RECT 1.575 7.54 1.805 25.42;
  RECT 1.575 7.98 1.955 25.42;
 LAYER M1 SPACING 0.23;
  RECT 0 0 12.25 6.32;
  RECT 0 0 10.285 6.46;
  RECT 0 0 9.905 6.48;
  RECT 10.775 0 12.25 6.495;
  RECT 1.715 0 9.905 26.5;
  RECT 1.575 7.54 10.285 26.5;
  RECT 0 7.675 10.285 26.5;
  RECT 10.775 7.52 12.25 26.5;
  RECT 11.375 0 12.25 26.5;
  RECT 0 7.68 12.25 26.5;
 LAYER M2;
  RECT 1.625 7.93 1.905 26.5;
  RECT 0.385 25.105 3.89 26.5;
  RECT 0 26 3.89 26.5;
  RECT 0 0 4.135 0.5;
  RECT 0.45 0 4.135 1.105;
  RECT 0.45 0 0.73 6.48;
  RECT 4.43 7.93 4.71 24.505;
  RECT 4.43 1.705 4.71 6.09;
  RECT 5.785 1.705 6.065 6.09;
  RECT 10.02 8.03 10.3 26.5;
  RECT 11.465 8.03 11.745 26.5;
```

```
RECT 5.73 22.35 12.045 24.505;
   RECT 5.91 22.35 12.045 24.91;
   RECT 6.27 22.35 12.045 26.5;
   RECT 6.27 26 12.25 26.5;
   RECT 6.82 0 12.25 0.5;
   RECT 6.82 0 11.75 1.105;
   RECT 10.03 0 10.31 6.09;
   RECT 11.47 0 11.75 6.09;
  LAYER M2 SPACING 0.28;
   RECT 6.64 0 12.25 6.27;
   RECT 0 0 4.315 6.43;
   RECT 0.45 0 0.73 6.48;
   RECT 1.765 1.525 9.855 24.685;
   RECT 1.765 1.135 4.71 25.09;
   RECT 5.785 1.135 9.855 25.09;
   RECT 5.73 7.73 12.25 25.09;
   RECT 0 7.725 4.07 26.5;
   RECT 6.09 7.73 12.25 26.5;
  LAYER M3 SPACING 0.28;
   RECT 0 0 4.315 25.09;
   RECT 0 1.525 12.25 24.685;
   RECT 0 1.135 4.71 25.09;
   RECT 5.785 1.135 12.25 25.09;
   RECT 5.73 1.525 12.25 25.09;
   RECT 0 0 4.07 26.5;
   RECT 6.64 0 12.25 26.5;
   RECT 6.09 1.135 12.25 26.5;
  LAYER M4 SPACING 0.28;
   RECT 0 0 12.25 26.5;
  LAYER M5 SPACING 0.28;
   RECT 0 0 12.25 26.5;
  LAYER TOP M SPACING 0.46;
   RECT 0 0 12.25 26.5;
 END
END 2T TX Z0d AL
```

# **END LIBRARY**

Delete the blue lines of the lef file (note that if there is some lines with property before the nd library, you should also delete it).

# 2. Make lef file for the digital controller

This is an easy process, first, open the layout of your digital controller in encounter and then use the command

```
lefOut ***.lef
```

Pad: Pcornerur NW

#### That's it

```
3. Make the top.io file based on your chip
  # Silicon Perspective, A Cadence Company
                                      #
  # FirstEncounter IO Assignment
                                   #
  Version: 2of
  Pad: PAD G00 E
  Pad: PAD I00 E
  Pad: PAD_G01 E
  Pad: PAD I01 E
  Pad: PAD_G02 E
  Pad: I10
               Ε
               Е
  Pad: I7
               Е
  Pad: 112
  Pad: PAD I02 E
  Pad: I6
               Е
  Pad: PAD I03 E
  Pad: I9
               E
  Orient: R90
  Pad: Pcornerlr NE
  Pad: PAD I07 N
  Pad: PAD G06 N
  Pad: PAD I06 N
  Pad: PAD G05 N
  Pad: PAD I05 N
  Pad: PAD I04 N
  Pad: I8
               N
  Pad: 116
               N
  Pad: PAD G04 N
  Pad: 115
               N
  Pad: PAD G03 N
  Pad: I17
               N
  Orient: R180
```

```
Pad: PAD G10 W
Pad: PAD II1 W
Pad: PAD G09 W
Pad: PAD I10 W
Pad: PAD G08 W
Pad: PAD I09 W
Pad: I5
              W
Pad: 118
              W
Pad: PAD I08 W
Pad: I14
              W
Pad: I13
              W
Pad: PAD G07 W
Orient: R270
Pad: Pcornerul SW
```

Pad: PAD\_I12 S
Pad: PAD\_G11 S
Pad: PAD\_I13 S
Pad: PAD\_G12 S
Pad: PAD\_I14 S
Pad: PAD\_I15 S
Pad: PAD\_I16 S
Pad: PAD\_G13 S
Pad: PAD\_I17 S
Pad: I11 S
Pad: PAD\_I18 S
Pad: PAD\_G14 S
Orient: R0

Pad: Pcornerll SE

The PAD I or PAD G stands for the power pads (VDD and VSS)

# 4. Make a final top level schematic of your top circuit

This is an easy step, but make sure you make the lef file for all the first level blocks you used in the top level schematic.

# 5. Make an equivalent verilog file for the top level schematic (for example, call it core.v)

For this verilog log, we just need to illustrate the connection of the top level circuit, so it is not hard. But since we make it manually, take care of it, it's easy to make mistakes

```
modute core (CDF, DDF, ERES, ESSET, SERE), MEDI, COL. ESSET, DOJT, DOF, CLUSS, REC., DJ, CCC., DJ;

unitual CDJ, DDF, CLUSS, REC., DJ, RCL, DJT, CCC., CDJ;

unitual CDJ, DDF, CLUSS, REC., DJ, RCL, DJT, CCC., DCJ;

unitual CDJ, DDF, CLUSS, REC., DJ, RCL, DJT, CCC., DCJ;

unitual CDJ, DDF, CLUSS, REC., DJT, RCL, DJT, CCC., DCJ;

unitual CDJ, DDF, CLUSS, REC., DJT, RCL, DJT, CCC., DCJ, DJT, CLUSS, RCL, DJT, RCL, DJT, CLUSS, RCL, DJT, R
```

An example for this top level verilog

6. Connect the pads with the inputs and outputs of your top level circuit

Since the pads are blocks and we need to connect the pads with the inputs and outputs of the core, so we need to make connection of them

```
module top();

wire wire_CGC_TEST;
wire wire_CLK;
wire wire_DIN;
wire wire_RDEN;
wire wire_RESET;
wire wire_START;
wire wire_TX_IN;
wire wire_WREN;
wire wire_A2T_OUT;
wire wire_CGC_OUT;
wire wire_CLKOS;
wire wire_DOUT;
wire wire_ENDF;
wire wire_RGC_OUT;
```

```
wire net1000;
wire net1001;
specify
  specparam CDS_LIBNAME = "testLib";
  specparam CDS CELLNAME = "top";
  specparam CDS VIEWNAME = "schematic";
endspecify
core I0(.CGC TEST(wire CGC TEST)
,.CLK(wire CLK)
"DIN(wire DIN)
,.RDEN(wire RDEN)
,.RESET(wire RESET)
"START(wire START)
"TX IN(wire TX IN)
,.WREN(wire WREN)
"A2T OUT(wire A2T OUT)
,.CGC_OUT(wire_CGC_OUT)
,.CLKOS(wire CLKOS)
,.DOUT(wire DOUT)
,.ENDF(wire ENDF)
"RGC OUT(wire RGC OUT)
);
pv0i PAD G00 (.VSS(VSS));
pv0a PAD G01 (.VSS(VSS));
pv0i PAD G02 (.VSS(VSS));
pv0a PAD G03 (.VSS(VSS));
pv0i PAD G04 (.VSS(VSS));
pv0a PAD G05 (.VSS(VSS));
pv0i PAD G06 (.VSS(VSS));
pv0a PAD G07 (.VSS(VSS));
pv0i PAD G08 (.VSS(VSS));
pv0a PAD G09 (.VSS(VSS));
pv0i PAD G10 (.VSS(VSS));
pv0a PAD G11 (.VSS(VSS));
pv0i PAD G12 (.VSS(VSS));
pv0a PAD G13 (.VSS(VSS));
pv0i PAD G14 (.VSS(VSS));
pvdi PAD I00 (.VDD(VDD));
pvda PAD I01 (.VDD(VDD));
pvdi PAD I02 (.VDD(VDD));
```

```
pvda PAD I03 (.VDD(VDD));
pvdi PAD I04 (.VDD(VDD));
pvda PAD I05 (.VDD(VDD));
pvdi PAD I06 (.VDD(VDD));
pvda PAD I07 (.VDD(VDD));
pvdi PAD I08 (.VDD(VDD));
pvda PAD I09 (.VDD(VDD));
pvdi PAD I10 (.VDD(VDD));
pvda PAD I11 (.VDD(VDD));
pvdi PAD I12 (.VDD(VDD));
pvda PAD I13 (.VDD(VDD));
pvdi PAD I14 (.VDD(VDD));
pvda PAD I15 (.VDD(VDD));
pvdi PAD I16 (.VDD(VDD));
pvda PAD I17 (.VDD(VDD));
pvdi PAD I18 (.VDD(VDD));
pc3d01 I5 (.CIN(wire CGC TEST), .PAD(net100));
pc3d01 I6 ( .CIN(wire_CLK), .PAD(net101));
pc3d01 I7 (.CIN(wire DIN), .PAD(net102));
pc3d01 I8 (.CIN(wire RDEN), .PAD(net103));
pc3d01 I9 (.CIN(wire RESET), .PAD(net104));
pc3d01 I10 (.CIN(wire START), .PAD(net105));
pc3d01 I11 (.CIN(wire TX IN), .PAD(net106));
pc3d01 I12 (.CIN(wire WREN), .PAD(net107));
pt3o01 I13 (.PAD(net108), .I(wire A2T OUT));
pt3o01 I14 (.PAD(net109), .I(wire CGC OUT));
pt3o01 I15 (.PAD(net110), .I(wire CLKOS));
pt3o01 I16 (.PAD(net111), .I(wire DOUT));
pt3o01 I17 (.PAD(net112), .I(wire ENDF));
pt3o01 I18 (.PAD(net113), .I(wire RGC OUT));
pfrelr Pcornerlr();
pfrelr Pcornerll();
pfrelr Pcornerur();
pfrelr Pcornerul();
endmodule
```

We give wire name for the pads and map the pads with the correct pins name and this is the top verilog file, we call it top.v

# 7. Encounter stage

#### a. Load file first

Almost the name as we used in the backend stage of the digital process, however, need to make some modifications.

```
### CTE::manc_default

suppressMessage ENCENT-2799

### act defilierChar / set defilierChar / set fe_core_to_left 100

### set fe_core_to_left 100

### set fe_core_to_left 100

### set fe_core_to_left 100

### set init_cos_search_lib ()

### set init_cos_search_lib ()

### set init_cos_search_lib ()

### set init_cos_left 100

### set init_pu_net () () () (design_in/to_p_u)

### set init_pu_net () () (design_in/to_p_u)

### set init_pu_net () () (design_in/to_p_u)

### set init_pu_net () () () (design_in/to_p_u)

### set init_pu_net () (design_in/to_p_u)

### set init_pu_net () (design_in/to_p_u)

### set init_pu_net () (design_in/to_p_u)
```

First, add the top.io in the script

Second, add the lef file in the set init\_lef\_file, which includes all the lef files we had

b. Add the iofill in the manual/ run the iofill script addIoFiller -cell pfeed30000 -prefix pfeed addIoFiller -cell pfeed10000 -prefix pfeed addIoFiller -cell pfeed02000 -prefix pfeed addIoFiller -cell pfeed01000 -prefix pfeed addIoFiller -cell pfeed00540 -prefix pfeed addIoFiller -cell pfeed00120 -prefix pfeed addIoFiller -cell pfeed00120 -prefix pfeed addIoFiller -cell pfeed00040 -prefix pfeed addIoFiller -cell pfeed00010 -prefix pfeed

Make sure there is no empty space between the pads after the iofill script, it is very hard to fix it in virtuoso

c. Then do the power grid generation, and route stage as usual and finally stramOut the gds file as we did before for the digital controller

# 8. DRC

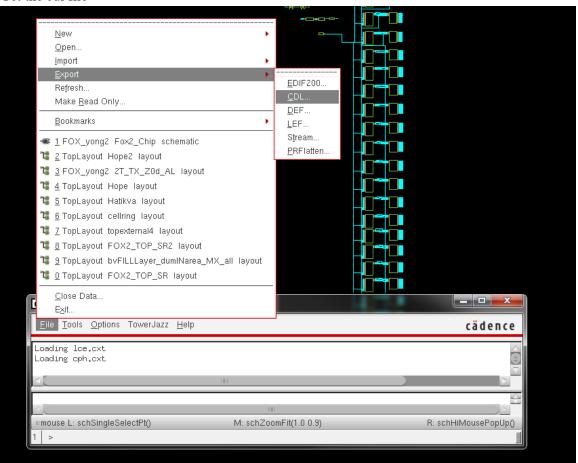
The same process we did to the digital controller, but if the power grid and the connection of the power grid to the pads are not connected. You must fix it manually in encounter

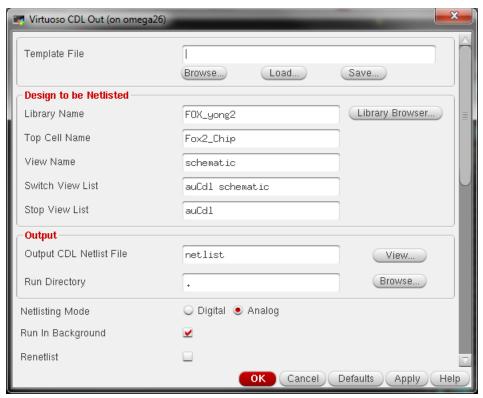
- Dummy fill if needed
   Since this is the final chip layout, sometimes it is needed to add the dummy layers for the fabrication consideration. For details, consult Goel
- b. Run the DRC check after dummy, the same method as we did before

# 9. LVS

After get the final layout, we need to get the netlist for the LVS check. The method we used here is export the cdl file and run the LVS between the layout and the cdl file

a. Get the cdl file





Then click  $\rightarrow$  OK/Apply

b. Make necessary changes to the cdl file

Since the digital controller here is the system level verilog file, we cannot use this cdl for the LVS with the layout. in the digital controller process, we had the cdl file for the digital controller only, thus, we can manually edit the top cdl file and replace the definition digital controller in this file with the digital controller from the digital part (v2cdl command from the gate level verilog)

While for the instance of the digital controller, make sure the pin name order is the same as the cdl definition part

c. Run the final LVS, the same technique as we use in the digital controller part